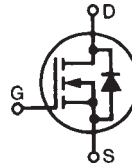


Polar™ HiPerFET Power MOSFET

IXFK 180N15P IXFX 180N15P

N-Channel Enhancement Mode
Fast Intrinsic Diode
Avalanche Rated



$$V_{DSS} = 150 \text{ V}$$

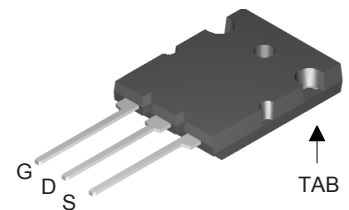
$$I_{D25} = 180 \text{ A}$$

$$R_{DS(on)} \leq 11 \text{ m}\Omega$$

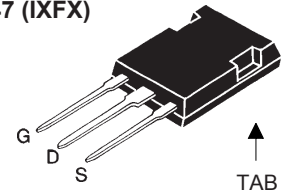
$$t_{rr} \leq 200 \text{ ns}$$

| Symbol | Test Conditions | Maximum Ratings | |
|--------------|---|-----------------|------------------|
| | | | |
| V_{DSS} | $T_J = 25^\circ\text{C to } 175^\circ\text{C}$ | 150 | V |
| V_{DGR} | $T_J = 25^\circ\text{C to } 175^\circ\text{C}; R_{GS} = 1 \text{ M}\Omega$ | 150 | V |
| V_{DS} | Continuous | ± 20 | V |
| V_{GSM} | Transient | ± 30 | V |
| I_{D25} | $T_C = 25^\circ\text{C}$ | 180 | A |
| $I_{D(RMS)}$ | External lead current limit | 75 | A |
| I_{DM} | $T_C = 25^\circ\text{C}$, pulse width limited by T_{JM} | 380 | A |
| I_{AR} | $T_C = 25^\circ\text{C}$ | 60 | A |
| E_{AR} | $T_C = 25^\circ\text{C}$ | 100 | mJ |
| E_{AS} | $T_C = 25^\circ\text{C}$ | 4 | J |
| dv/dt | $I_S \leq I_{DM}$, $di/dt \leq 100 \text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DSS}$ $T_J \leq 150^\circ\text{C}$, $R_G = 4 \Omega$ | 10 | V/ns |
| P_D | $T_C = 25^\circ\text{C}$ | 830 | W |
| T_J | | -55 ... +175 | $^\circ\text{C}$ |
| T_{JM} | | 175 | $^\circ\text{C}$ |
| T_{stg} | | -55 ... +150 | $^\circ\text{C}$ |
| T_L | 1.6 mm (0.062 in.) from case for 10 s | 300 | $^\circ\text{C}$ |
| T_{SOLD} | Plastic body for 10 s | 260 | $^\circ\text{C}$ |
| M_d | Mounting torque (IXFK) | 1.13/10 | Nm/lb.in. |
| F_c | Mounting Force (IXFX) | 20..120/4.5..25 | N/lb |
| Weight | TO-264 (IXFK) | 10 | g |
| | PLUS247 (IXFX) | 6 | g |

TO-264 (IXFK)



PLUS247 (IXFX)



G = Gate D = Drain
S = Source TAB = Drain

| Symbol | Test Conditions | Characteristic Values | | |
|--------------|---|-----------------------|------|----------------------|
| | | Min. | Typ. | Max. |
| BV_{DSS} | $V_{GS} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$ | 150 | | V |
| $V_{GS(th)}$ | $V_{DS} = V_{GS}$, $I_D = 4 \text{ mA}$ | 2.5 | | 5.0 V |
| I_{GSS} | $V_{GS} = \pm 20 \text{ V}_{DC}$, $V_{DS} = 0$ | | | $\pm 200 \text{ nA}$ |
| I_{DSS} | $V_{DS} = V_{DSS}$ $V_{GS} = 0 \text{ V}$ $T_J = 150^\circ\text{C}$ | | | 25 μA |
| | | | | 250 μA |
| $R_{DS(on)}$ | $V_{GS} = 10 \text{ V}$, $I_D = 0.5 I_{D25}$ Note 1 | | | 11 $\text{m}\Omega$ |

Features

- † International standard packages
- † Unclamped Inductive Switching (UIS) rated
- † Low package inductance
- easy to drive and to protect

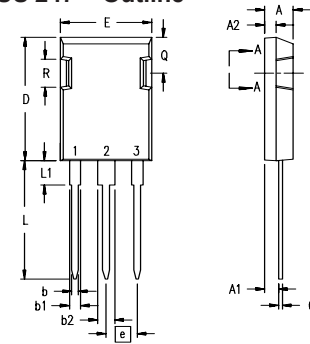
Advantages

- † Easy to mount
- † Space savings
- † High power density

| Symbol | Test Conditions | Characteristic Values | | |
|--------------|---|--|------|------------------------|
| | | $(T_J = 25^\circ\text{C}, \text{ unless otherwise specified})$ | | |
| | | Min. | Typ. | Max. |
| g_{fs} | $V_{DS} = 10\text{ V}; I_D = 0.5 I_{D25}$, Note 1 | 55 | 86 | S |
| C_{iss} | $V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$ | | 7000 | pF |
| C_{oss} | | | 2250 | pF |
| C_{rss} | | | 515 | pF |
| $t_{d(on)}$ | $V_{GS} = 10\text{ V}, V_{DS} = 0.5 V_{DSS}, I_D = 60\text{ A}$ $R_G = 3.3\ \Omega$ (External) | | 30 | ns |
| t_r | | | 32 | ns |
| $t_{d(off)}$ | | | 150 | ns |
| t_f | | | 36 | ns |
| $Q_{g(on)}$ | $V_{GS} = 10\text{ V}, V_{DS} = 0.5 V_{DSS}, I_D = 0.5 I_{D25}$ | | 240 | nC |
| Q_{gs} | | | 55 | nC |
| Q_{gd} | | | 140 | nC |
| R_{thJC} | | | | 0.18°C/W |
| R_{thCS} | | 0.15 | | $^\circ\text{C/W}$ |

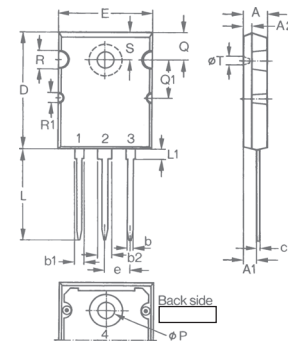
| Symbol | Test Conditions | Characteristic Values | | |
|----------|---|--|------|--------|
| | | $(T_J = 25^\circ\text{C}, \text{ unless otherwise specified})$ | | |
| | | Min. | Typ. | Max. |
| I_s | $V_{GS} = 0\text{ V}$ | | | 180 A |
| I_{SM} | Repetitive | | | 380 A |
| V_{SD} | $I_F = 90\text{ A}, V_{GS} = 0\text{ V}$, Note 1 | | | 1.3 V |
| t_{rr} | $I_F = 25\text{ A}, -di/dt = 100\text{ A}/\mu\text{s}$ $V_R = 100\text{ V}, V_{GS} = 0\text{ V}$ | | 150 | 200 ns |
| Q_{RM} | | | 0.6 | |

Note 1: Pulse test, $t \leq 300\ \mu\text{s}$, duty cycle $d \leq 2\%$

PLUS 247™ Outline


Terminals: 1 - Gate
2 - Drain (Collector)
3 - Source (Emitter)
4 - Drain (Collector)

| Dim. | Millimeter | | Inches | |
|----------------|------------|-------|----------|-------|
| | Min. | Max. | Min. | Max. |
| A | 4.83 | 5.21 | .190 | .205 |
| A ₁ | 2.29 | 2.54 | .090 | .100 |
| A ₂ | 1.91 | 2.16 | .075 | .085 |
| b | 1.14 | 1.40 | .045 | .055 |
| b ₁ | 1.91 | 2.13 | .075 | .084 |
| b ₂ | 2.92 | 3.12 | .115 | .123 |
| C | 0.61 | 0.80 | .024 | .031 |
| D | 20.80 | 21.34 | .819 | .840 |
| E | 15.75 | 16.13 | .620 | .635 |
| e | 5.45 BSC | | .215 BSC | |
| L | 19.81 | 20.32 | .780 | .800 |
| L1 | 3.81 | 4.32 | .150 | .170 |
| Q | 5.59 | 6.20 | .220 | 0.244 |
| R | 4.32 | 4.83 | .170 | .190 |

TO-264 AA Outline


| Dim. | Millimeter | | Inches | |
|----------------|------------|-------|----------|-------|
| | Min. | Max. | Min. | Max. |
| A | 4.82 | 5.13 | .190 | .202 |
| A ₁ | 2.54 | 2.89 | .100 | .114 |
| A ₂ | 2.00 | 2.10 | .079 | .083 |
| b | 1.12 | 1.42 | .044 | .056 |
| b ₁ | 2.39 | 2.69 | .094 | .106 |
| b ₂ | 2.90 | 3.09 | .114 | .122 |
| c | 0.53 | 0.83 | .021 | .033 |
| D | 25.91 | 26.16 | 1.020 | 1.030 |
| E | 19.81 | 19.96 | .780 | .786 |
| e | 5.46 BSC | | .215 BSC | |
| J | 0.00 | 0.25 | .000 | .010 |
| K | 0.00 | 0.25 | .000 | .010 |
| L | 20.32 | 20.83 | .800 | .820 |
| L1 | 2.29 | 2.59 | .090 | .102 |
| P | 3.17 | 3.66 | .125 | .144 |
| Q | 6.07 | 6.27 | .239 | .247 |
| Q1 | 8.38 | 8.69 | .330 | .342 |
| R | 3.81 | 4.32 | .150 | .170 |
| R1 | 1.78 | 2.29 | .070 | .090 |
| S | 6.04 | 6.30 | .238 | .248 |
| T | 1.57 | 1.83 | .062 | .072 |

IXYS reserves the right to change limits, test conditions, and dimensions.

| | | | | | | | | |
|--|-----------|-----------|-----------|-----------|--------------|--------------|-------------|--------------|
| IXYS MOSFETs and IGBTs are covered by | 4,835,592 | 4,931,844 | 5,049,961 | 5,237,481 | 6,162,665 | 6,404,065 B1 | 6,683,344 | 6,727,585 |
| one or more of the following U.S. patents: | 4,850,072 | 5,017,508 | 5,063,307 | 5,381,025 | 6,259,123 B1 | 6,534,343 | 6,710,405B2 | 6,759,692 |
| | 4,881,106 | 5,034,796 | 5,187,117 | 5,486,715 | 6,306,728 B1 | 6,583,505 | 6,710,463 | 6,771,478 B2 |

Fig. 1. Output Characteristics @ 25°C

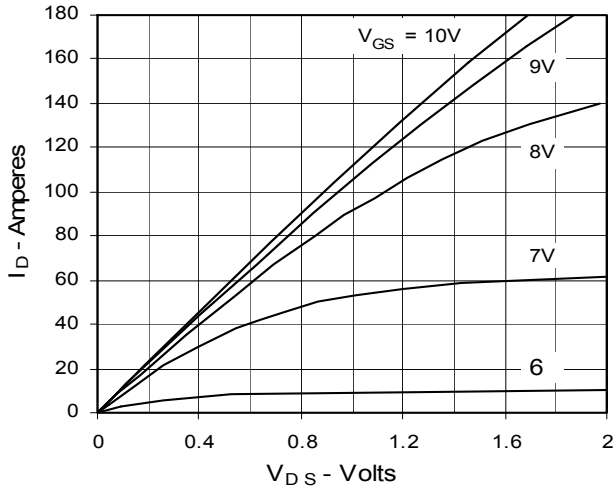


Fig. 2. Extended Output Characteristics @ 25°C

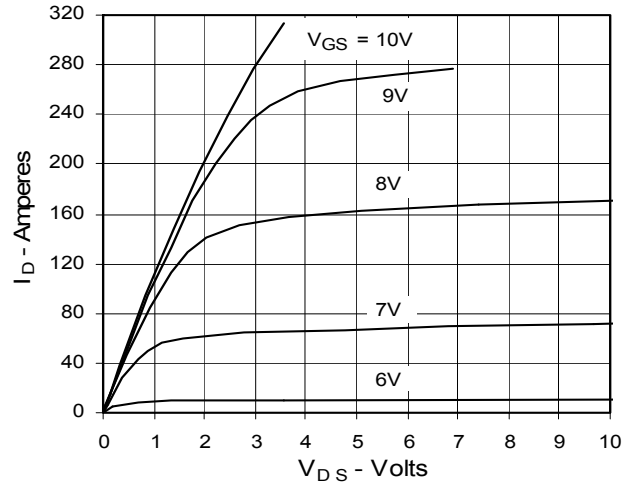


Fig. 3. Output Characteristics @ 150°C

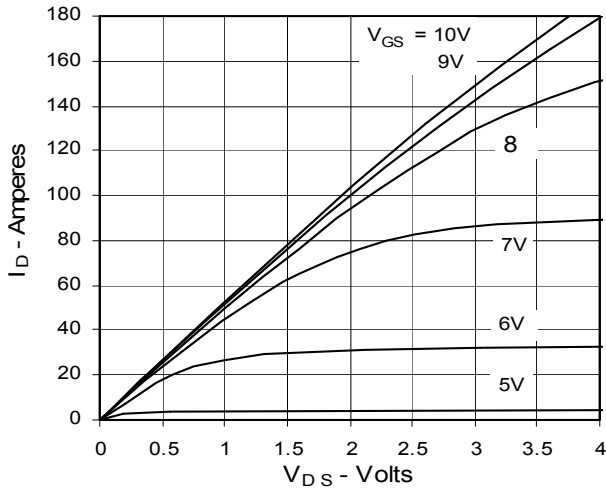


Fig. 4. $R_{DS(on)}$ Normalized to 0.5 I_{D25} Value vs. Junction Temperature

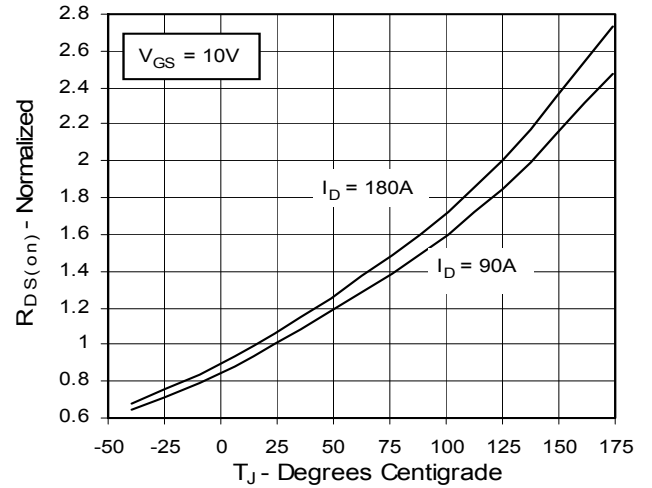


Fig. 5. $R_{DS(on)}$ Normalized to 0.5 I_{D25} Value vs. Drain Current

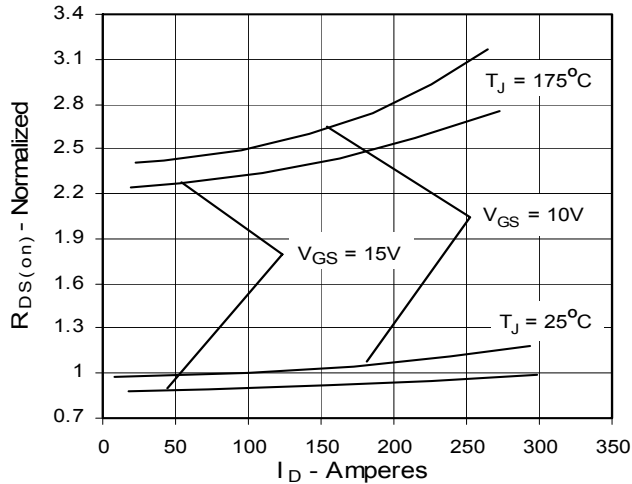


Fig. 6. Drain Current vs. Case Temperature

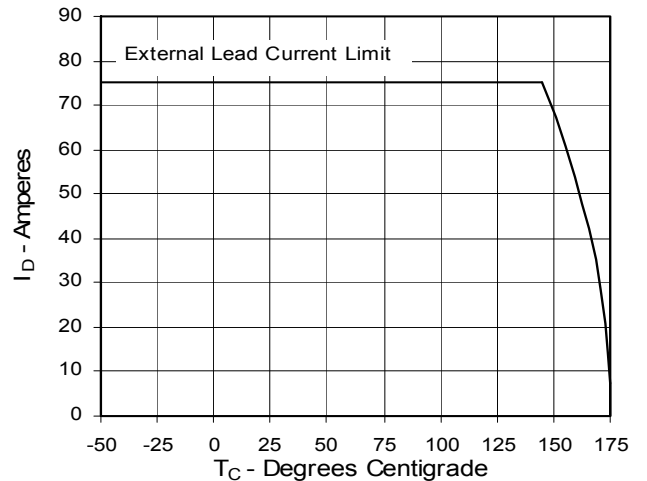


Fig. 7. Input Admittance

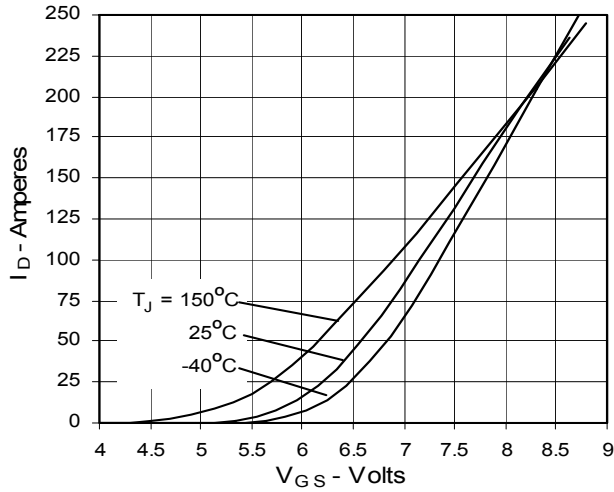


Fig. 8. Transconductance



Fig. 9. Source Current vs. Source-To-Drain Voltage

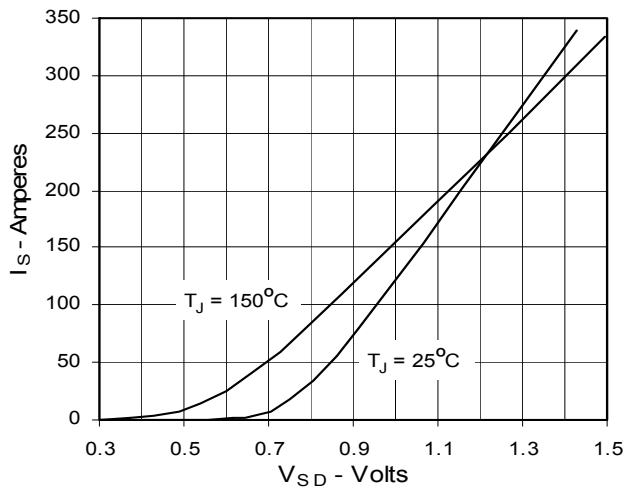


Fig. 10. Gate Charge

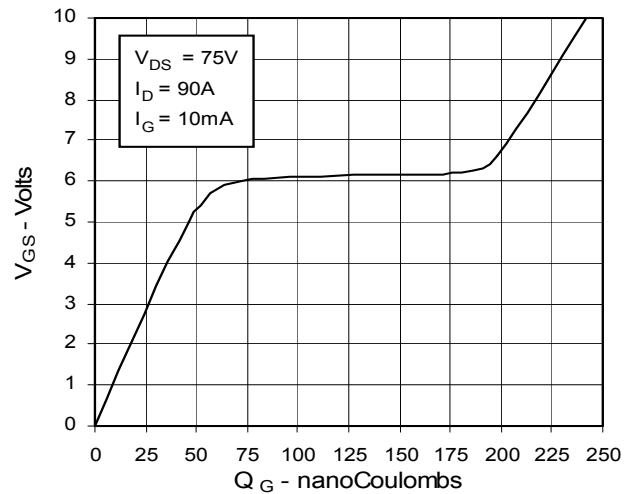


Fig. 11. Capacitance

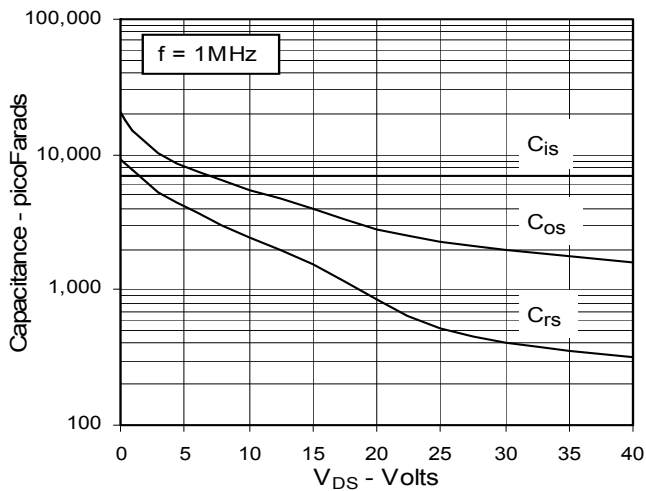


Fig. 12. Forward-Bias Safe Operating Area

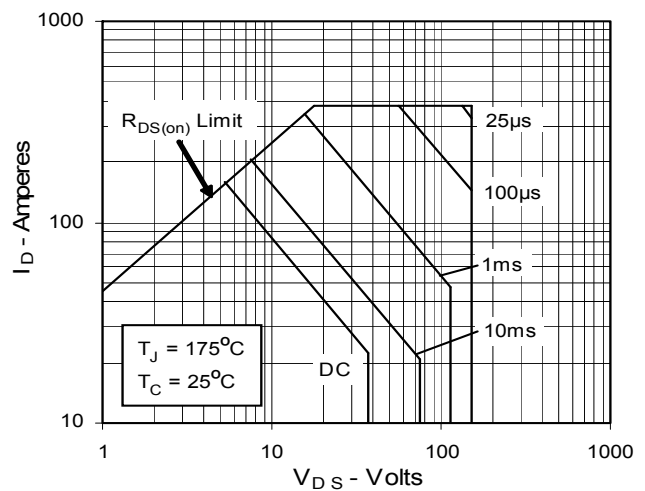
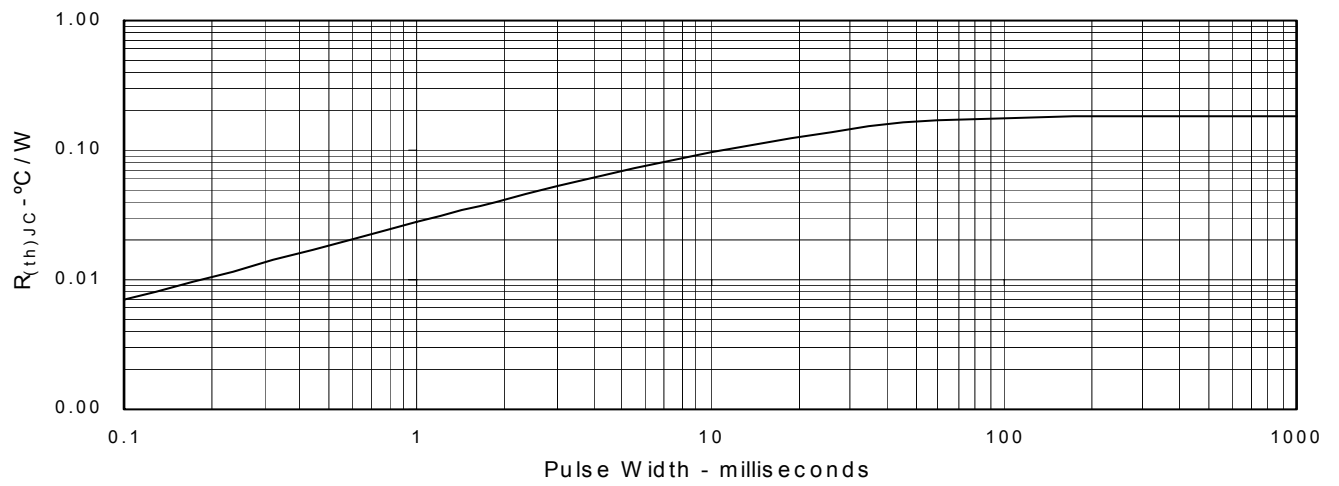


Fig. 13. Maximum Transient Thermal Resistance





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